



Material Content Data Sheet



Sales Product Name		BSC009NE2LS5I		Issued		25. January 2018		
MA#		MA001382772						
Package		PG-TDSON-8-7		Weight*		115.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.699	0.60	0.60	6025	6025
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		424	
	non noble metal	copper	7440-50-8	49.082	42.33	42.38	423213	423764
	non noble metal	copper	7440-50-8	0.021	0.02	0.02	179	179
wire	non noble metal	copper	7440-50-8	0.021	0.02	0.02	179	179
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		710	
	plastics	epoxy resin	-	5.849	5.04		50431	
	inorganic material	silicondioxide	60676-86-0	35.257	30.40	35.51	304005	355146
leadfinish	non noble metal	tin	7440-31-5	1.452	1.25	1.25	12517	12517
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1427	1427
solder	non noble metal	tin	7440-31-5	0.020	0.02		170	
	noble metal	silver	7440-22-4	0.025	0.02		212	
	non noble metal	lead	7439-92-1	0.939	0.81	0.85	8098	8480
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		58	
	non noble metal	iron	7439-89-6	0.022	0.02		192	
	non noble metal	copper	7440-50-8	22.292	19.22	19.25	192212	192462
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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